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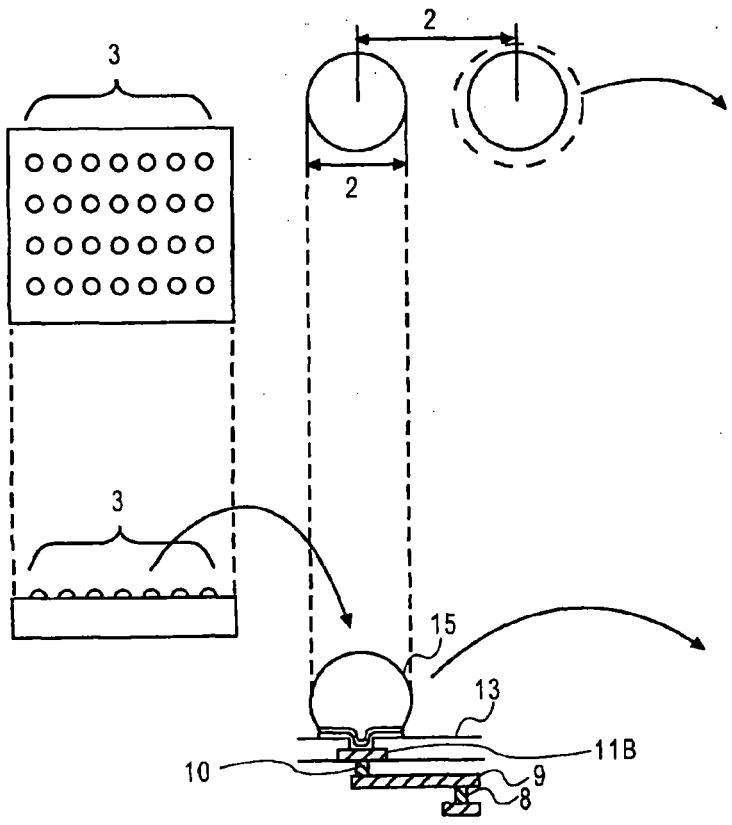
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(54) Title: BALL LIMITING METALLURGY FOR INPUT/OUTPUTS AND METHODS OF FABRICATION



(57) Abstract: The present invention is an input/ouput for a device and it method of fabrication. The input/output of the present invention comprises a bond pad having a ball limiting metallurgy (BLM) formed thereon and a bump formed on the ball limiting metallurgy (BLM). In an embodiment of the present invention the ball limiting metallurgy comprises a first film comprising nickel, vanadium, and nitrogen. In the second embodiment of the present invention the bump limiting metallurgy includes a first alloy film comprising a nickel-niobium alloy.

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